

CCAF-01 Aluminum-base copper-clad laminate

The company : changzhou chaoshun electronic technique Co.,Ltd

The test base : CCAF-01 the high heat dissipation Aluminum-base copper-clad laminate

Thickness of the copper : 18um, 35um, 70um

Thickness of the dielectric : 70um

Thickness of the aluminum-base : 1.5mm

The result of the test :

Item	Test item		Technology request	Unit	Test result
1	Peel Strength	A	≥ 1.8	N/mm	2.0
		After thermal stress (260℃)	≥ 1.8	N/mm	1.8
2	Blister test After Thermal stress (288℃, 2min)		288℃ 2 min No delaminating NO blister	/	Ok
3	Flammability(A)		FV-O	/	FV-O
4	thermal resistance		≤ 2.0	℃/W	1.0
5	Thermal Conductivity			W/m-k	1.0
6	Surface Resistivity	A	$\geq 1 \times 10^5$	MΩ	5×10^7
		Constant humidity treatment (90%,35℃,96h)	$\geq 1 \times 10^5$	MΩ	2×10^6
7	Volume Resistivity	A	$\geq 1 \times 10^6$	MΩ·m	4×10^8
		Constant humidity treatment (90%,35℃,96h)	$\geq 1 \times 10^6$	MΩ·m	5×10^7
8	Dielectric Breakdown		≥ 2	Kv	2.2
9	Permittivity (1MHz) (40℃, 93%, 96h)		≤ 4.4	/	4.2
10	Loss Tangent (1MHz) (40℃, 93%, 96h)		≤ 0.03	/	0.02

Remarks: Typical values for reference only